

IN THE CLAIMS:

1. to 10. (Canceled).

11. (Original) A process for producing a laminate, comprising the step of thermocompression bonding a core insulating layer, a thermoplastic resin layer, which is disposed on both sides or one side (z-plane) of the core insulating layer, has an adhesive property and has a minimum value of the storage modulus of not more than 10^6 Pa at a temperature at or above T_g of the thermoplastic resin layer, and a metal layer disposed on the surface of the thermoplastic resin layer to one another at a temperature of T_g or above.

12. (Original) The process for producing the laminate according to claim 11, wherein the thermocompression bonding is carried out under temperature conditions such that the storage modulus of the thermoplastic resin is minimum.

13. (New) A method for producing an electronic circuit comprising the steps of:

providing a laminate comprising a combination of a metal layer with an insulating layer, said laminate having a layer construction of first metal layer/insulating layer/second metal layer or a layer construction of metal layer/insulating layer, the insulating layer having a multilayer structure of two or more layers, the layer on the side of the adhesive interface with the metal layer, out of the layers constituting the insulating layer, being a thermoplastic resin layer, and a maximum value of the storage modulus at a temperature at or above T_g of the thermoplastic resin layer being not more than 10^6 Pa;

forming a photosensitive resin layer on a surface of the metal layer of the laminate; and

patterning the thus formed photosensitive resin layer to prepare an electronic circuit.

14. (New) A method for producing an electronic circuit comprising the steps of:

providing an insulating film comprising an insulating layer and a thermoplastic resin layer provided on at least one side of the insulating layer, the thermoplastic resin having a maximum value of the storage modulus of not more than 10^6 Pa at a temperature at or above T_g of the thermoplastic resin layer;

laminating the insulating film with a metal layer to prepare a laminate;

forming a photosensitive resin layer on a surface of the metal layer of the laminate; and

patterning the thus formed photosensitive resin layer to prepare an electronic circuit.